



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Tae Heon Lee et al.)	Confirmation No.	8528
)		
Serial No.:	10/763,859)	Art Unit:	2814
)		
Filed:	01/23/2004)	Examiner:	Cao, Phat X.
)		
For:	Semiconductor Package Having)		
	Reduced Thickness)		

AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Restriction Requirement mailed March 21, 2005 in relation to the above-identified divisional patent application, please amend the application as follows: